

# RELIABILITY TEST RESULT

Product name : S-8581Ax-A8TxU7

Package type : HSNT-8(2030)

| No. | Test item   | Test Condition  | Test Time   | r/n  | Criterion   |
|-----|---|---|-------------|------|---|
| 1   | High-temperature operation                            | Ta=125 °C, V=Vopr max.                                      | 1000 h      | 0/22 | Satisfies the product standard  |
| 2   | Temperature humidity bias #1                          | Ta=85 °C, RH=85 %, V=Vopr max.                              | 1000 h      | 0/22 | Satisfies the product standard  |
| 3   | Pressure cooker bias #1                               | Ta=130 °C, RH=85 %, P=2.3×10 <sup>5</sup> Pa<br>V=Vopr max. | 96 h        | 0/22 | Satisfies the product standard  |
| 4   | Storage in high temperature                           | Ta=150 °C   | 1000 h      | 0/22 | Satisfies the product standard  |
| 5   | Storage in low temperature                            | Ta=-65 °C   | 1000 h      | 0/22 | Satisfies the product standard  |
| 6   | Temperature Cycle (Gas phase) #1                      | Ta=150 °C ⇔ -65 °C<br>15 minutes for each                   | 500 cycles  | 0/22 | Satisfies the product standard  |
| 7   | Resistance to soldering heat<br>(reflow soldering) #2 | T=260 °C ,10 s  | 3 times     | 0/22 | Satisfies the product standard<br>No abnormality by appearances   |
| 8   | Solderability #3                                      | T=245 °C<br>Solder material : Sn-3.0Ag-0.5Cu                | 5 s         | 0/11 | Zero cross time should be less than 3 seconds.<br>Solder should be applied at 95% or more of solderability judgment area. |
| 9   | Whisker - 1<br>(Temperature / Humidity Storage)       | Ta=30 °C, RH=60%  | 4000 h      | 0/6  | Whisker should be less than 40μm  |
| 10  | Whisker - 2<br>(Temperature Cycling)                  | Ta=85 °C ⇔ -40 °C   | 1500 cycles | 0/6  | Whisker should be less than 45μm  |
| 11  | Whisker - 3<br>(High Temperature / Humidity Storage)  | Ta=55 °C, RH=85 %   | 4000 h      | 0/6  | Whisker should be less than 40μm  |
| 12  | Solder Joint Reliability<br>(shear test) #3           | Ta=125 °C ⇔ -40 °C<br>Solder material : Sn-3.0Ag-0.5Cu      | 2000 cycles | 0/22 | After temperature cycle test, keep strength for shear stress more than the 50 % of initial mean value.                    |
| 13  | ESD - 1 (Human Body Model)                            | V=±2000 V, C=100 pF, R=1.5 kΩ<br>Ground : VIN / VSS         | 5 pulses    | 0/5  | Satisfies the product standard  |
| 14  | ESD - 2 (Charged Device Model)                        | V=±500V charged, discharged                                 | 1 pulse     | 0/5  | Satisfies the product standard  |
| 15  | Latch up 1<br>(Pulsed current injection test)         | ±100 mA, V =Vopr max.                                       | 1 pulse     | 0/5  | No latch up   |
| 16  | Latch up 2<br>(Vsupply overvoltage test)              | The overvoltage specified when<br>V = Vopr max.             | 1 pulse     | 0/5  | No latch up   |

Remark : Vopr max. =Maximum operation voltage

#1,2,3 : Each test designated # is performed after Pre-Treatment finished.

Pre-Treatment consists of High Temperature Storage ,Temperature Humidity Storage and Soldering Heat. (See the table below.)

| Pre Treatment (#1)  |                                |                                      |
|---------------------|--------------------------------|--------------------------------------|
| High Temp. Storage  | Temperature Humidity Storage   | Soldering Heat                       |
| Ta=125 °C<br>t=24 h | Ta=85 °C<br>RH=85 %<br>t=168 h | Reflow 3 times<br>T=260 °C<br>t=10 s |

| Pre Treatment (#2)  |                                |                |
|---------------------|--------------------------------|----------------|
| High Temp. Storage  | Temperature Humidity Storage   | Soldering Heat |
| Ta=125 °C<br>t=24 h | Ta=85 °C<br>RH=85 %<br>t=168 h | —              |

| Pre Treatment (#3) |                                |                |
|--------------------|--------------------------------|----------------|
| High Temp. Storage | Temperature Humidity Storage   | Soldering Heat |
| —                  | Ta=105 °C<br>RH=100 %<br>t=8 h | —              |